

PCN Number:	20180912002.1		PCN Date:	Sep 14, 2018	
Title:	Qualification of AIZU as an additional Wafer Fab Site option for devices in the DDC264 product family				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Dec 14, 2018	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its AIZU fabrication facility as an additional Wafer Fab source for the selected devices listed in "Product Affected" section.

Current Sites			Additional Sites		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DP1DM5	HPA07	200mm	AIZU	HPA07	200mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
AIZU	CU2	JPN	Aizuwakamatsu-shi

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750





(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (Y) 0033317
(20L) CS0: SHE (21L) CC0: USA
(22L) AS0: MLA (23L) AC0: MYS

Product Affected Group:

DDC264CKZAW	DDC264CZAW	DDC264CZAWR	SN1611002ZAWR
DDC264CKZAWR			

Qualification Report

Qualify Aizu Die G4DDC264GAP for DDC264CKZAWR

Approved – 08/20/2018

Product Attributes

Attributes	Qual Device: DDC264CKZAWR	QBS Product Reference: DDC1128ZKL_DIEREVG	QBS Product Reference: DDC1128ZKL_DIEREVF	QBS Product Reference: DDC264CKZAW	QBS Package Reference: SN0711033ZCL
Assembly Site	AK4	AK4	AK4	AK4	AP3
Package Family	BGA	BGA	BGA	BGA	BGA
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	AIZU	DMOS5	DMOS5	DMOS5	DM5
Wafer Process	HFA07	HFA07	HFA07	HFA07	A035

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL3-260C: DDC264CKZAWR, DDC1128ZKL, SN1611002ZAWR
- Devices contain multiple dies: DDC264CKZAWR, SN1611002ZAWR, DDC1128ZKL

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DDC264CKZAWR	QBS Product/Process Reference: DDC1128ZKL_DIEREVG	QBS Product/Process Reference: DDC1128ZKL_DIEREVF	QBS Product Reference: DDC264CKZAW	QBS Package Reference: SN0711033ZCL
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass	Pass
FLAM	Flammability (IEC 695-2-2)	--	-	1/5/0	2/10/0	-	-
FLAM	Flammability (UL 94V-0)	--	-	1/5/0	2/10/0	-	-
FLAM	Flammability (UL-1694)	--	-	1/5/0	2/10/0	-	-
HAST	Biased HAST, 110C/85%RH	264 Hours	-	1/77/0	2/154/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0
HBM	ESD - HBM	500 V	1/3/0	-	-	-	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	1/77/0	2/154/0	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	-	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	1/77/0	2/154/0	-	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-	-	3/18/0
PD	Physical Dimensions	-	-	1/5/0	2/10/0	-	3/15/0
SBS	Solder Ball Shear	Solder Balls	-	-	-	-	2/154/0
SD	Solderability	Pb	-	1/22/0	2/44/0	-	-
SD	Surface Mount Solderability	Pb Free	-	1/22/0	2/44/0	-	-
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	1/77/0	2/154/0	1/77/0	3/231/0-
TS	Thermal Shock, -55/125C	700 Cycles	-	1/77/0	2/154/0	-	-
UHAST	Unbiased HAST, 110C/85%RH	264 Hours	-	1/77/0	2/154/0	1/77/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	-	1/76/0	2/121/0	-	3/150/0
WBS	Ball Bond Shear	Wires	-	1/76/0	2/121/0	-	3/150/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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